Power MOSFET

100 V, 46 m Ω , 19 A, Single N-Channel

Features

- Small Footprint (5x6 mm) for Compact Design
- Low R_{DS(on)} to Minimize Conduction Losses
- Low Q_G and Capacitance to Minimize Driver Losses
- NVMFS6B85NLWF Wettable Flank Option for Enhanced Optical Inspection
- AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free and are RoHS Compliant

MAXIMUM RATINGS (T_J = 25°C unless otherwise noted)

Parameter			Symbol	Value	Unit
Drain-to-Source Voltage			V_{DSS}	100	V
Gate-to-Source Voltage			V_{GS}	±16	V
Continuous Drain Current R _{B.IC}	Steady State	$T_C = 25^{\circ}C$	I _D	19	Α
(Notes 1, 2, 3)		T _C = 100°C		14	
Power Dissipation		$T_C = 25^{\circ}C$	P_{D}	42	W
R _{θJC} (Notes 1, 2)		T _C = 100°C		21	
Continuous Drain		T _A = 25°C	I _D	5.6	Α
Current $R_{\theta JA}$ (Notes 1, 2, 3)	Steady	T _A = 100°C		4.0	
Power Dissipation	State	T _A = 25°C	P_{D}	3.5	W
R _{θJA} (Notes 1 & 2)		T _A = 100°C		1.75	
Pulsed Drain Current	$T_A = 25$	°C, t _p = 10 μs	I _{DM}	93	Α
Operating Junction and Storage Temperature			T _J , T _{stg}	-55 to + 175	°C
Source Current (Body Diode)			IS	32	Α
Single Pulse Drain-to-Source Avalanche Energy (I _{L(pk)} = 1.7 A)			E _{AS}	116	mJ
Lead Temperature for Soldering Purposes (1/8" from case for 10 s)			T _L	260	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL RESISTANCE MAXIMUM RATINGS

Parameter	Symbol	Value	Unit
Junction-to-Case - Steady State	$R_{\theta JC}$	3.6	°C/W
Junction-to-Ambient - Steady State (Note 2)	$R_{\theta JA}$	43	

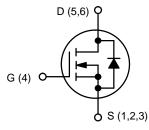
- The entire application environment impacts the thermal resistance values shown, they are not constants and are only valid for the particular conditions noted.
- 2. Surface-mounted on FR4 board using a 650 mm², 2 oz. Cu pad.
- Maximum current for pulses as long as 1 second is higher but is dependent on pulse duration and duty cycle.



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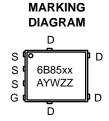
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V _{(BR)DSS}	R _{DS(ON)} MAX	I _D MAX
400.14	46 mΩ @ 10 V	40.4
100 V	72 mΩ @ 4.5 V	19 A



N-CHANNEL MOSFET





6B85NL = NVMFS6B85NL 6B85LW = NVMFS6B85NLWF A = Assembly Location

Y = Year
W = Work Week
ZZ = Lot Traceability

ORDERING INFORMATION

See detailed ordering, marking and shipping information on page 5 of this data sheet.

ELECTRICAL CHARACTERISTICS (T_J = 25°C unless otherwise specified)

Parameter	Symbol	Test Condition		Min	Тур	Max	Unit
OFF CHARACTERISTICS	•				-	-	-
Drain-to-Source Breakdown Voltage	V _{(BR)DSS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		100			V
Drain-to-Source Breakdown Voltage Temperature Coefficient	V _{(BR)DSS} / T _J				64		mV/°C
Zero Gate Voltage Drain Current	I _{DSS}	$V_{GS} = 0 \text{ V},$ $V_{DS} = 80 \text{ V}$	T _J = 25°C			10	μΑ
			T _J = 125°C			250	
Gate-to-Source Leakage Current	I _{GSS}	V _{DS} = 0 V, V _{GS} = 16 V				100	nA
ON CHARACTERISTICS (Note 4)							
Gate Threshold Voltage	V _{GS(TH)}	$V_{GS} = V_{DS}, I_D = 250 \mu A$		1.2		2.4	V
Threshold Temperature Coefficient	V _{GS(TH)} /T _J				-5.2		mV/°C
		V _{GS} = 10 V			37	46	mΩ
Drain-to-Source On Resistance	R _{DS(on)}	V _{GS} = 4.5 V	I _D = 10 A		55	72	
CHARGES, CAPACITANCES & GATE RE	SISTANCE		•				•
Input Capacitance	C _{ISS}	V _{GS} = 0 V, f = 1 MHz, V _{DS} = 25 V			480		pF
Output Capacitance	C _{OSS}				170		
Reverse Transfer Capacitance	C _{RSS}				15		
	_	V _{GS} = 4.5 V, V _{DS} = 50 V; I _D = 10 A			3.8		
Total Gate Charge	Q _{G(TOT)}	V _{GS} = 10 V, V _{DS} = 50 V; I _D = 10 A			7.9		1
Threshold Gate Charge	Q _{G(TH)}				1.1		nC
Gate-to-Source Charge	Q _{GS}				2.4		
Gate-to-Drain Charge	Q_{GD}				1.1		
Plateau Voltage	V_{GP}				4.0		V
SWITCHING CHARACTERISTICS (Note 5)				1	1	•
Turn-On Delay Time	t _{d(ON)}	$V_{GS} = 4.5 \text{ V}, V_{DS} = 50 \text{ V},$ $I_{D} = 10 \text{ A}, R_{G} = 2.5 \Omega$			6.9		ns
Rise Time	t _r				66.9		
Turn-Off Delay Time	t _{d(OFF)}				12.5		
Fall Time	t _f				55.9		
DRAIN-SOURCE DIODE CHARACTERIS	TICS						
Forward Diode Voltage	V _{SD}	V _{GS} = 0 V, I _S = 10 A	T _J = 25°C		0.88	1.2	
			T _J = 125°C		0.76		V
Reverse Recovery Time	t _{RR}	$V_{GS} = 0 \text{ V, dIS/dt} = 100 \text{ A/}\mu\text{s,}$ $I_{S} = 10 \text{ A}$			39.4		ns
Charge Time	t _a				22.7		
Discharge Time	t _b				16.7		
Reverse Recovery Charge	Q _{RR}				40		nC

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

4. Pulse Test: pulse width ≤ 300 μs, duty cycle ≤ 2%.

5. Switching characteristics are independent of operating junction temperatures.

TYPICAL CHARACTERISTICS

ID, DRAIN CURRENT (A)

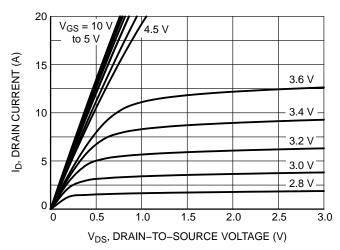


Figure 1. On-Region Characteristics

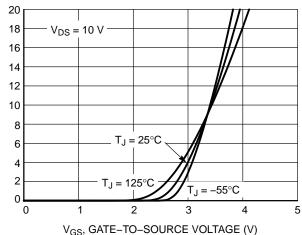


Figure 2. Transfer Characteristics

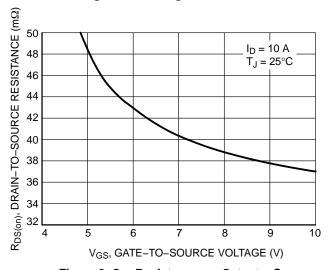


Figure 3. On-Resistance vs. Gate-to-Source Voltage

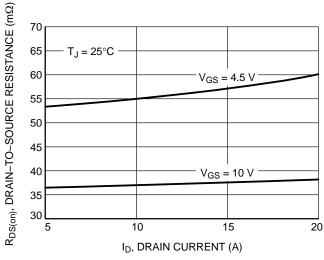


Figure 4. On–Resistance vs. Drain Current and Gate Voltage

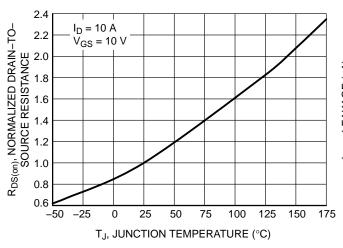


Figure 5. On–Resistance Variation with Temperature

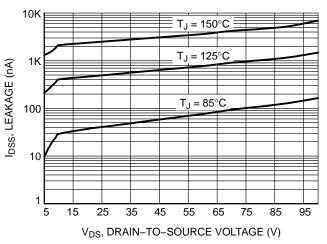
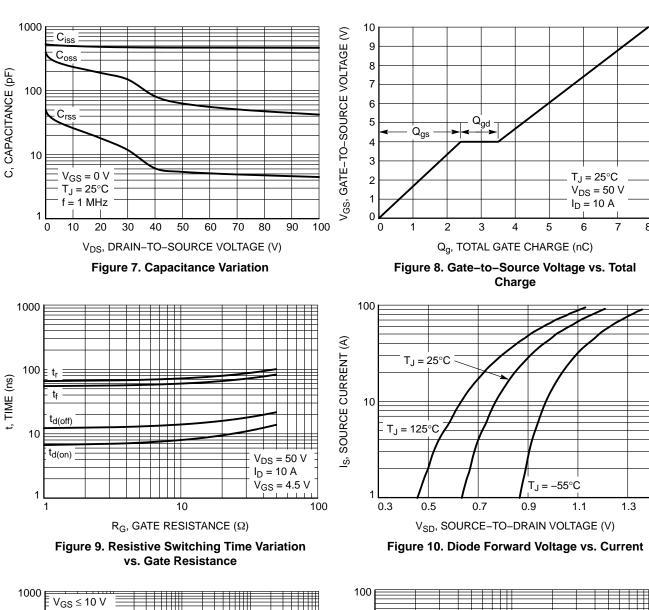


Figure 6. Drain-to-Source Leakage Current vs. Voltage

TYPICAL CHARACTERISTICS



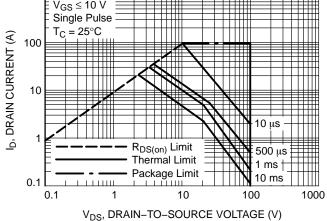


Figure 11. Maximum Rated Forward Biased Safe Operating Area

T_{AV}, TIME IN AVALANCHE (sec) **Figure 12.** I_{PEAK} vs. T_{AV}

100 (V) TJ(initial) = 100°C TJ(initial) = 25°C

TYPICAL CHARACTERISTICS

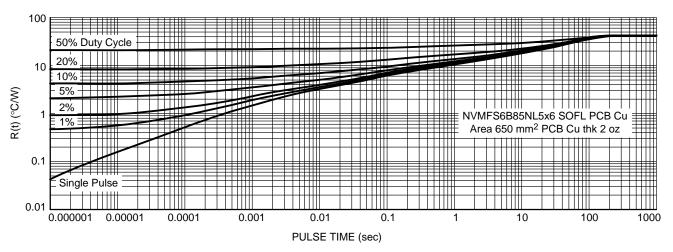


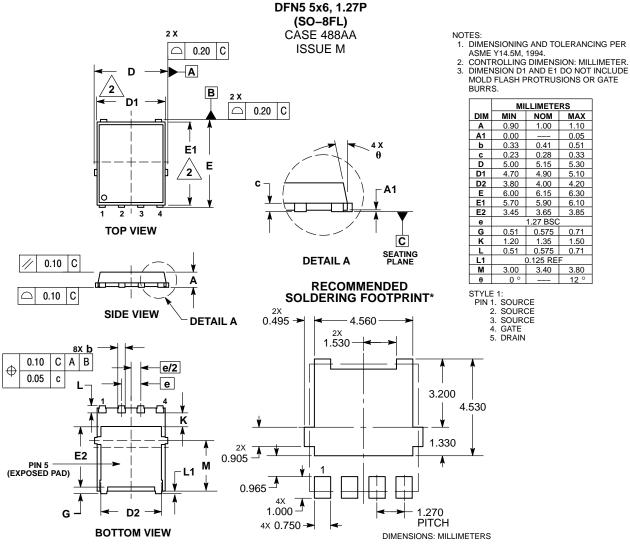
Figure 13. Thermal Response

DEVICE ORDERING INFORMATION

Device	Marking	Package	Shipping [†]
NVMFS6B85NLT1G	6B85NL	DFN5 (Pb-Free)	1500 / Tape & Reel
NVMFS6B85NLWFT1G	6B85LW	DFN5 (Pb-Free, Wettable Flanks)	1500 / Tape & Reel
NVMFS6B85NLT3G	6B85NL	DFN5 (Pb-Free)	5000 / Tape & Reel
NVMFS6B85NLWFT3G	6B85LW	DFN5 (Pb-Free, Wettable Flanks)	5000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

PACKAGE DIMENSIONS



*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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